



CHENMKO ENTERPRISE CO.,LTD

Halogens free devices

SURFACE MOUNT

P-Channel Enhancement Mode Field Effect Transistor

VOLTAGE 12 Volts CURRENT 9 Ampere

CHM5813ESQ2GP

APPLICATION

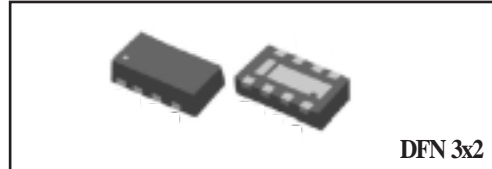
- * Power Management in Note Book
- * Portable Equipment
- * Battery Powered System
- * BLoad Switch
- * DSC

FEATURE

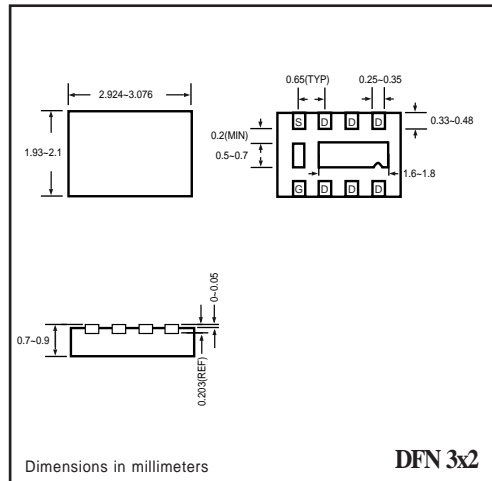
- * Small flat package. (DFN 3x2)
- * Super high density cell design for extremely low R_{DS(ON)}.
- * High power and current handing capability.

MARKING

- * M5813ES

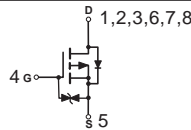


DFN 3x2



DFN 3x2

CIRCUIT



Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	CHM5813ESQ2GP	Units
V _{DSS}	Drain-Source Voltage	-12	V
V _{GSS}	Gate-Source Voltage	±8	V
I _D	Maximum Drain Current - Continuous	-9	A
	- Pulsed (Note 3)	-60	
P _D	Maximum Power Dissipation	2.5	W
T _J	Operating Temperature Range	-55 to 150	°C
T _{STG}	Storage Temperature Range	-55 to 150	°C

- Note : 1. Surface Mounted on FR4 Board , t <= 10sec
 2. Pulse Test , Pulse width <= 300us , Duty Cycle <= 2%
 3. Repetitive Rating , Pulse width limited by maximum junction temperature
 4. Guaranteed by design , not subject to production trsting

Thermal characteristics

R _{θJA}	Thermal Resistance, Junction-to-Ambient (Note 1)	50	°C/W
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ELECTRICAL CHARACTERISTIC (CHM5813ESQ2GP)

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Units
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OFF CHARACTERISTICS

BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = -250\ \mu\text{A}$	-12			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -12\text{ V}, V_{GS} = 0\text{ V}$			-1	μA
I_{GSSF}	Gate-Body Leakage	$V_{GS} = 8\text{ V}, V_{DS} = 0\text{ V}$			+100	nA
I_{GSSR}	Gate-Body Leakage	$V_{GS} = -8\text{ V}, V_{DS} = 0\text{ V}$			-100	nA

ON CHARACTERISTICS (Note 2)

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$	-0.4		-1	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = -1.8\text{ V}, I_D = -7.5\text{ A}$		20	31	$\text{m}\Omega$
		$V_{GS} = -2.5\text{ V}, I_D = -8.5\text{ A}$		15	25	
		$V_{GS} = -4.5\text{ V}, I_D = -9\text{ A}$		12	20	

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = -6\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$		2960		pF
C_{oss}	Output Capacitance			624		
C_{rss}	Reverse Transfer Capacitance			218		

SWITCHING CHARACTERISTICS (Note 4)

Q_g	Total Gate Charge	$V_{DS} = -6\text{ V}, I_D = -9\text{ A}$ $V_{GS} = -4.5\text{ V}$		35		nC
Q_{gs}	Gate-Source Charge			7		
Q_{gd}	Gate-Drain Charge			12		
t_{on}	Turn-On Time	$V_{DD} = -6\text{ V}$ $V_{GS} = -4.5\text{ V}$ $R_{GEN} = 3\ \Omega, R_L = 6\ \Omega$		60		nS
t_r	Rise Time			25		
t_{off}	Turn-Off Time			225		
t_f	Fall Time			72		

DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS

I_S	Drain-Source Diode Forward Current	(Note 1)			-9.0	A
V_{SD}	Drain-Source Diode Forward Voltage	$I_S = -9\text{ A}, V_{GS} = 0\text{ V}$			-1.2	V

RATING CHARACTERISTIC CURVES (CHM5813ESQ2GP)

Typical Electrical Characteristics

Figure 1. Output Characteristics

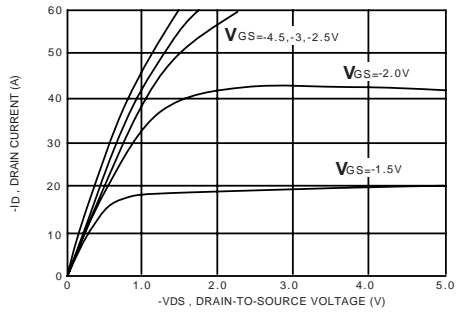


Figure 2. On-Resistance with Drain Current

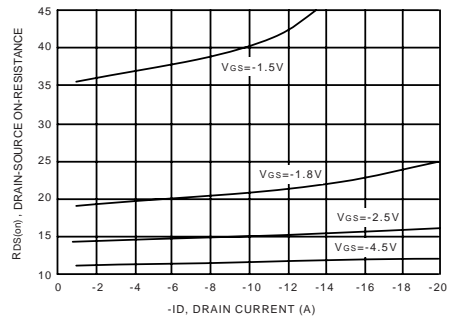


Figure 3. Gate Charge

